

ABSTRACT OF THE DISCLOSURE

A thin film bonding method and apparatus having structure for removing wetting agents applied to a thin film and base plate that are to be bonded by pressure and heat. A spray or rollers apply the wetting agent prior to the initial bonding of a leading edge of the thin film to a leading edge of the base plate. A pressure roller applies heat and pressure to the film and base plate, bonding them together as the roller rotates and drives the plate toward a cleaning position. Suction and agent removal rollers are used to remove the residual excess agent from the bonded film and the pressure roller. The removal rollers are joined together by a link mechanism that has a spring bias and is operation by a gear mechanism that provides a wiping action.

This Sheet Has Been Replaced

